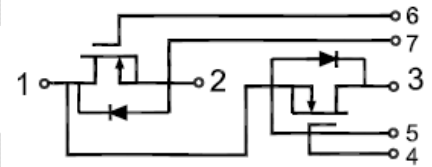


# MSC240HF120T2NH

## SiC MOSFET Module

### Features:

- Ultra Low Loss
- High-Frequency Operation
- Zero Reverse Recovery Current from Diode
- Zero Turn-off Tail Current from MOSFET
- Normally-off, Fail-safe Device Operation
- Easy of Paralleling
- Copper Baseplate and Aluminum Nitride Insulator



### Applications:

- UPS and SMPS
- Fast DC/DC Converter
- Solar and Wind Inverter
- Induction Heating/Welding

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Description	Conditions	Value	Unit
$V_{DSmax}$	Drain-Source Voltage		1200	V
$V_{GSmax}$	Gate-Source Voltage	Absolute Maximum Values	-10/+25	V
$V_{GSop}$	Gate-Source Voltage	Recommended Operational Values	-5/+20	V
$I_D$	Continuous Drain Current	$V_{GS}=20\text{V}, T_C=25^\circ\text{C}$	360	A
		$V_{GS}=20\text{V}, T_C=90^\circ\text{C}$	240	A
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}, T_{Jmax}=150^\circ\text{C}$	1340	W

**Electrical Characteristics of MOSFET ( $T_C=25^\circ\text{C}$  unless otherwise specified)**

Symbol	Description	Conditions	Min	Typ	Max	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = 10\text{V}, I_D = 15\text{mA}, T_J = 25^\circ\text{C}$		2.20		V
		$V_{DS} = 10\text{V}, I_D = 15\text{mA}, T_J = 125^\circ\text{C}$		1.65		V
$R_{DS(on)}$	On State Resistance	$V_{GS} = 20\text{V}, I_D = 240\text{A}, T_J = 25^\circ\text{C}$		6.0		m $\Omega$
		$V_{GS} = 20\text{V}, I_D = 240\text{A}, T_J = 125^\circ\text{C}$		10.0		m $\Omega$
$g_{fs}$	Transconductance	$V_{DS} = 20\text{V}, I_D = 240\text{A}, T_J = 25^\circ\text{C}$		90		S
		$V_{DS} = 20\text{V}, I_D = 240\text{A}, T_J = 125^\circ\text{C}$		78		S
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 1200\text{V}, V_{GS} = 0\text{V}$			1000	$\mu\text{A}$
$I_{GSS}$	Gate- Source Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = 20\text{V}$			$\pm 1$	$\mu\text{A}$
$C_{iss}$	Input Capacitance			11.4		nF
$C_{oss}$	Output Capacitance	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}, V_{AC} = 25\text{mV}$		1.5		nF
$C_{rss}$	Reverse Transfer Capacitance			66		pF

**Switching Characteristics**

$Q_g$	Total Gate Charge	$V_{DD} = 600\text{V}, I_D = 240\text{A}, V_{GS} = -5/20\text{V}$		590		nC
$Q_{gs}$	Gate-Source Charge			180		nC
$Q_{gd}$	Gate-Drain (Miller) Charge			222		nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 600\text{V}, I_D = 240\text{A}, R_G = 4.7\Omega, V_{GS} = -5/20\text{V}, \text{Inductive Load}, T_J = 25^\circ\text{C}$		140		ns
$t_r$	Rise Time			85		ns
$t_{d(off)}$	Turn-off Delay Time			260		ns
$t_f$	Fall Time			120		ns
$E_{on}$	Turn-on Switching Energy Loss			3.1		mJ
$E_{off}$	Turn-off Switching Energy Loss			6.3		mJ
$t_{d(on)}$	Turn-on Delay Time		$V_{DD} = 600\text{V}, I_D = 240\text{A}, R_G = 4.7\Omega, V_{GS} = -5/20\text{V}, \text{Inductive Load}, T_J = 125^\circ\text{C}$		120	
$t_r$	Rise Time			110		ns
$t_{d(off)}$	Turn-off Delay Time			290		ns
$t_f$	Fall Time			120		ns

$E_{on}$	Turn-on Switching Energy Loss	$V_{DD}=600V, I_D=240A,$ $R_G=4.7\Omega, V_{GS}=-5/20V,$ Inductive Load, $T_J=125^\circ C$		2.5		mJ
$E_{off}$	Turn-off Switching Energy Loss			6.6		mJ
$t_{SC}$	Short Time	$V_{DD}=700V, V_{GS}=15V, T_J=100^\circ C$	5			$\mu s$
$R_{\theta JC}$	MOSFET Thermal Resistance: Junction-To-Case			0.093		$^\circ C/W$

### Free-Wheeling SiC Schottky Diode Characteristics ( $T_C=25^\circ C$ unless otherwise specified)

Symbol	Description	Conditions		Min	Typ	Max	Unit
$V_F$	Forward Voltage	$I_F=240A$	$T_J=25^\circ C$		1.8	2.0	V
			$T_J=125^\circ C$		2.3		
$Q_C$	Total Capacitive Charge	$V_R=1200V, T_J=25^\circ C$			776		$\mu C$
$R_{\theta JC}$	Diode Thermal Resistance: Junction-To-Case			0.144		$^\circ C/W$	

### Module

Symbol	Description	Conditions	Min	Typ	Max	Unit
$T_{Jmax}$	Junction Temperature		-40		150	$^\circ C$
$T_C, T_{STG}$	Case and Storage Temperature Range		-40		125	$^\circ C$
Visol	Case Isolation Voltage	AC, 50 Hz, 1 min	5.0			kV
$L_{Stray}$	Stray Inductance	Measured between terminals 2 and 3			15	nH
G	Weight			300		g
M	Mounting Torque	To heatsink and terminal			5	N·m
	Clearance Distance	Terminal to terminal			12	mm
	Creepage Distance	Terminal to terminal			30	mm
		Terminal to baseplate			40	mm

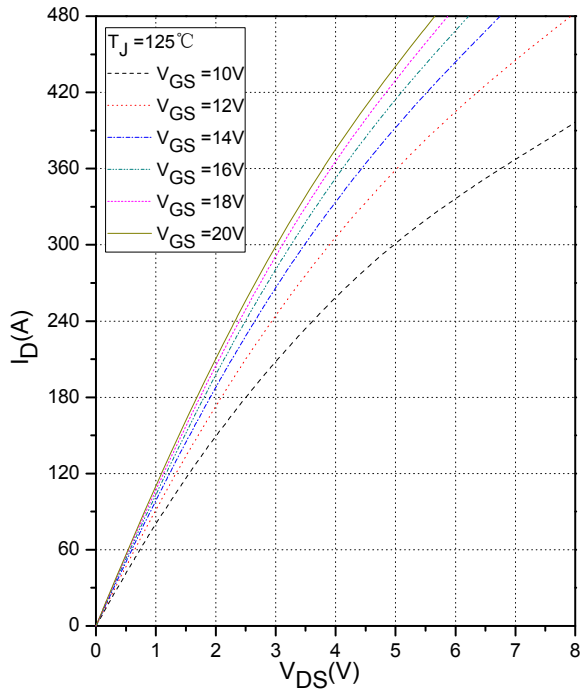


Fig.1 Typical Output Characteristics

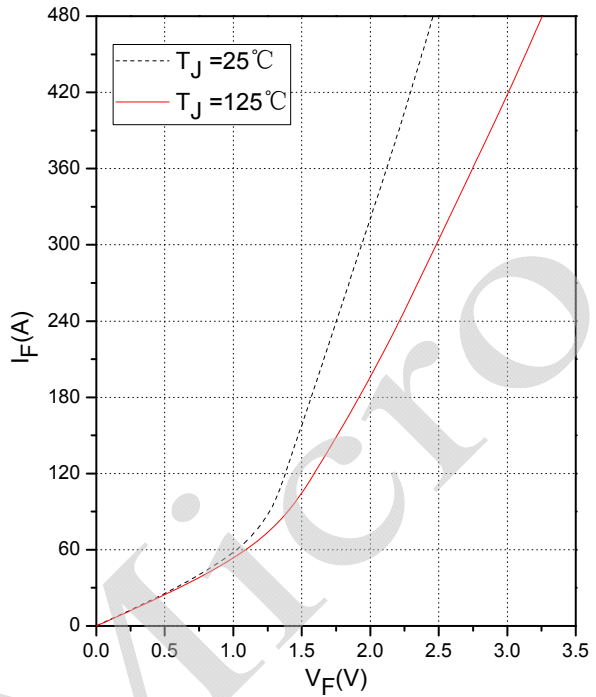


Fig.2 Forward Characteristics of Diode

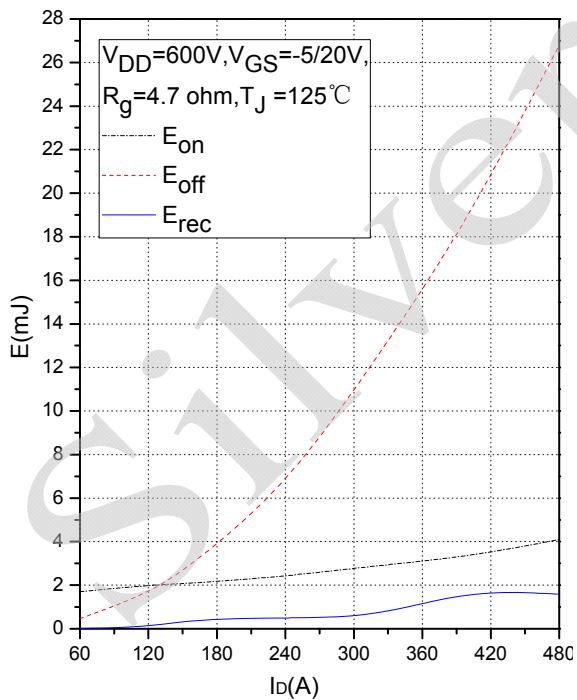


Fig.3 Typical Switching Loss vs. Drain Current

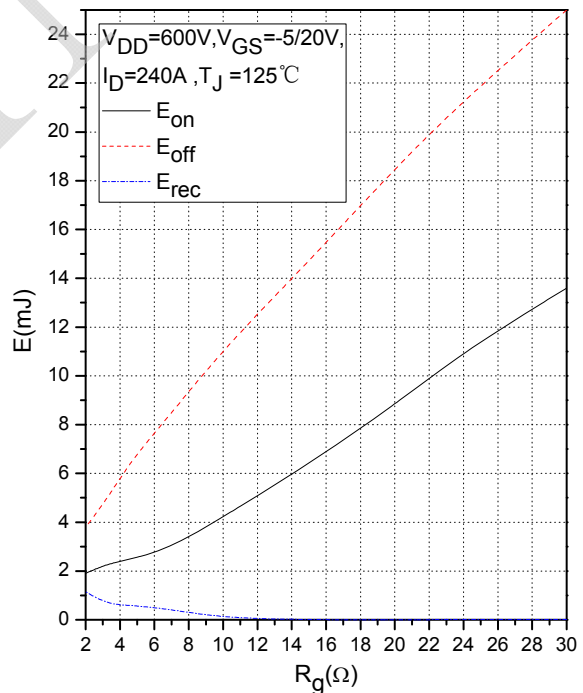
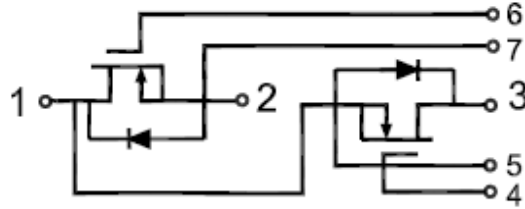
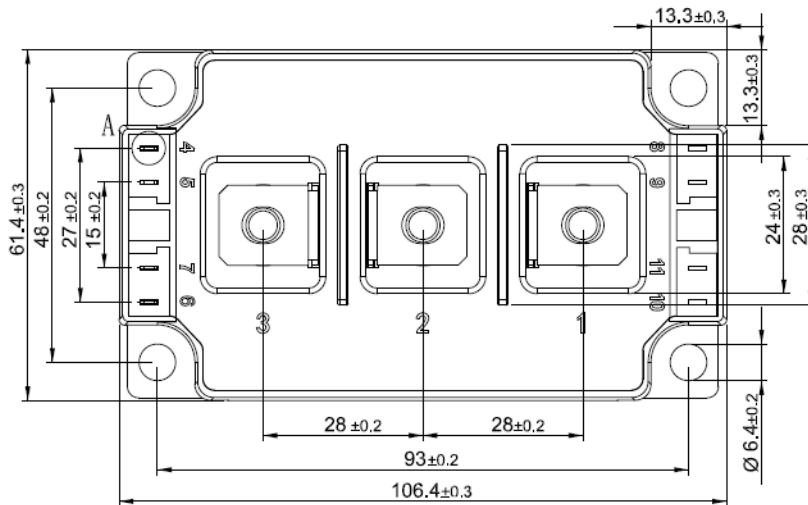
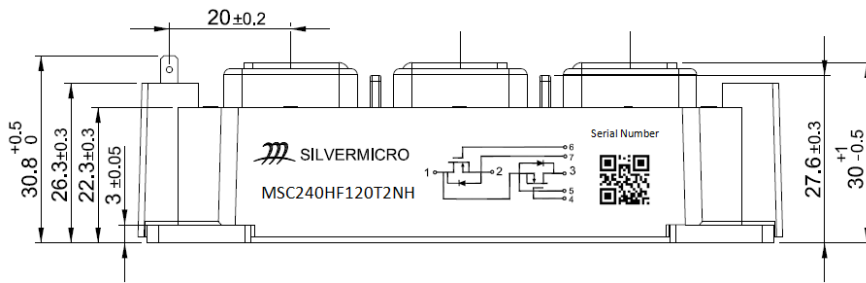


Fig.4 Typical Switching Loss vs. Gate Resistance

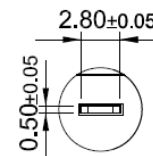
### Internal Circuit



### Package Outline (Unit: mm):



View A  
scale 3:1





Date	Revision	Notes
12/27/2018	01	Initial Release
01/24/2019	02	Add t <sub>sc</sub>

## Announcement

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